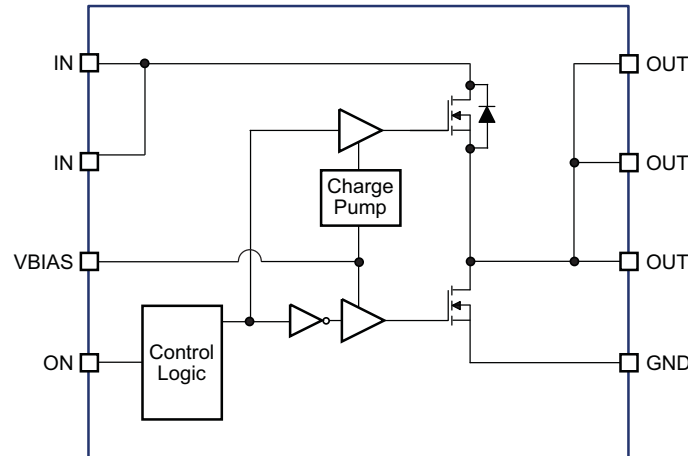






## Functional Block Diagram



## Absolute Maximum Ratings

Exceeding the Absolute Maximum ratings may damage the device.

Parameter	Rating
IN, ON, VBIAS, OUT to GND	-0.3V to 6V
Junction Temperature ( $T_J$ )	+150°C
Storage Temperature ( $T_S$ )	-65°C to +150°C
ESD Rating HBM/CDM	2kV/1kV

## Recommend Operating Ratings

The device is not guaranteed to operate beyond the Maximum Operating Ratings.

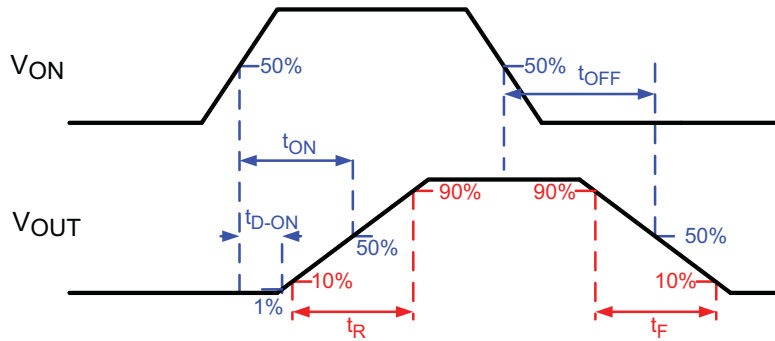
Parameter	Rating
Supply Voltage ( $V_{IN}$ )	5.5V
Ambient Temperature ( $T_A$ )	-40°C to +85°C
Package Thermal Resistance 3x3 DFN-8 ( $\theta_{JC}$ ) 3x3 DFN-8 ( $\theta_{JA}$ )	8°C/W 60°C/W

## Electrical Characteristics

$T_A = 25^\circ\text{C}$ ,  $V_{BIAS} = 5\text{V}$ ,  $V_{IN} = 1.05\text{V}$ , unless otherwise specified. Specifications in **BOLD** indicate a temperature range of -40°C to +85°C.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$V_{IN}$	IN Supply Voltage	$V_{ON} = 5\text{V}$	0.8	1.05	5.5	V
$V_{BIAS}$	VBIAS Supply Voltage		2.5	5	5.5	V
$I_D$	Maximum Continuous Current	$V_{ON} = 5\text{V}$		10		A
$I_{PLS}$	Maximum Pulsed Switch Current	$V_{IN} = V_{ON} = 5\text{V}$ Pulse < 300 $\mu\text{s}$ , 2% Duty Cycle		12		A
$I_q$	Quiescent Supply Current of $V_{BIAS}$	$I_{OUT} = 0\text{V}$ , $V_{ON} = 5\text{V}$		60		$\mu\text{A}$
$I_{OFF}$	VBIAS Shutdown Supply Current	$V_{ON} = 0\text{V}$ , $V_{OUT} = 0\text{V}$			2	$\mu\text{A}$
$I_{INOFF}$	IN Shutdown Supply Current	$V_{ON} = 0\text{V}$ , $V_{OUT} = 0\text{V}$			2	$\mu\text{A}$
$I_{ON}$	ON Leakage Current	$V_{ON} = 5\text{V}$			1	$\mu\text{A}$
$V_{ONH}$	ON High Level Voltage		1.2			V
$V_{ONL}$	ON Low Level Voltage				0.5	V
<b>Switching ON Resistance</b>						
$R_{ON}$	Switch ON-State Resistance	$I_{OUT} = -6\text{A}$ , $V_{ON} = 5\text{V}$ , $V_{BIAS} = 5\text{V}$		4.5	5	m $\Omega$
		$I_{OUT} = -6\text{A}$ , $V_{ON} = 5\text{V}$ , $V_{BIAS} = 3.3\text{V}$		4.5	5	m $\Omega$
$R_{PD}$	Output Pull-Down Resistance	$I_{OUT} = 15\text{mA}$ , $V_{ON} = 0\text{V}$		220	300	$\Omega$

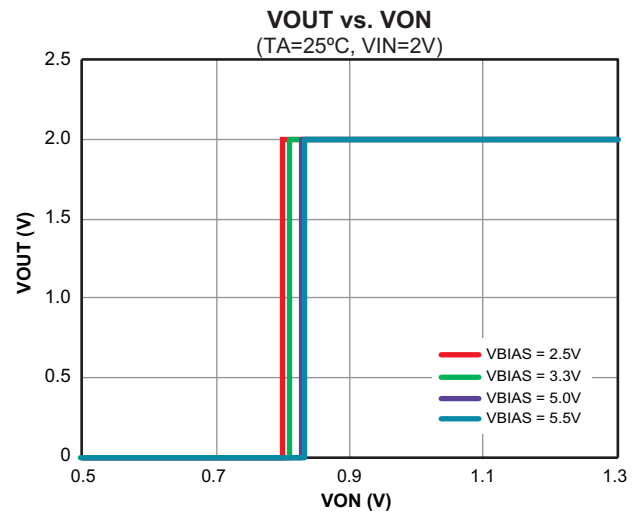
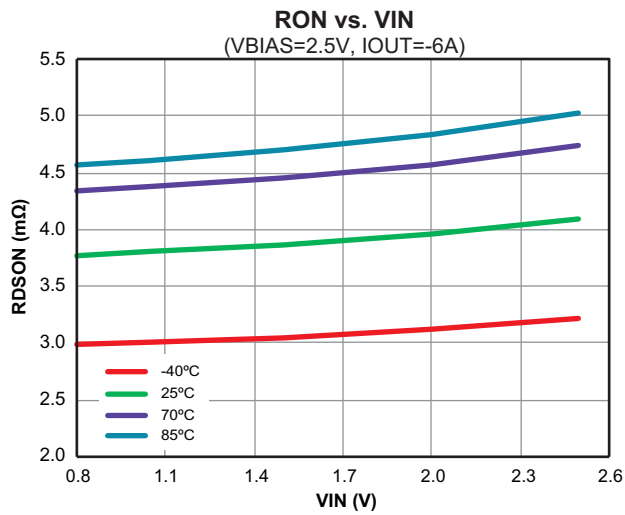
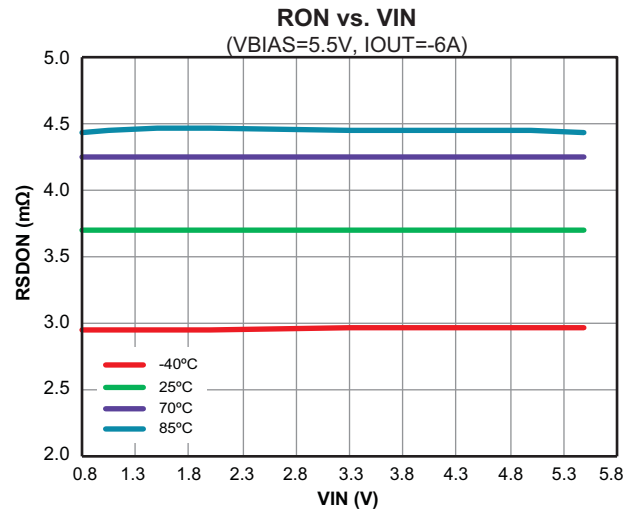
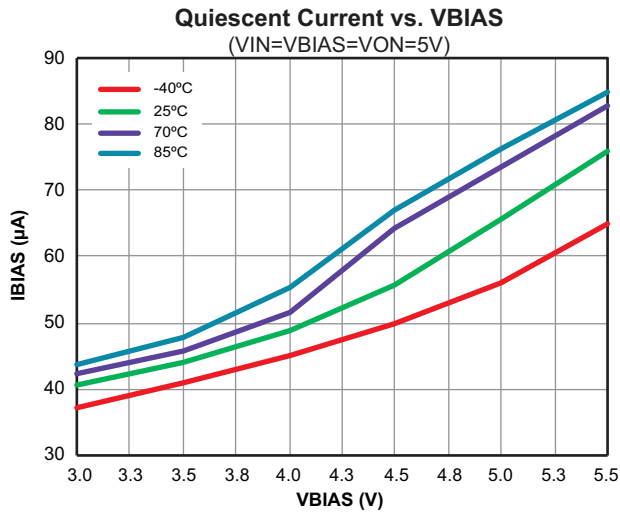
## Switching Characteristics



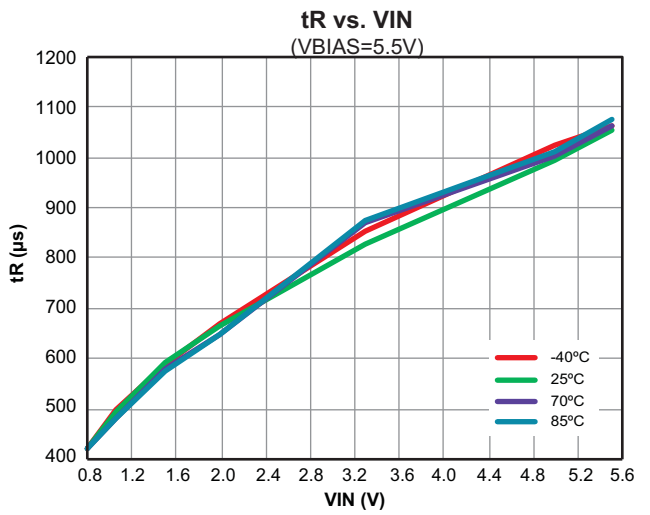
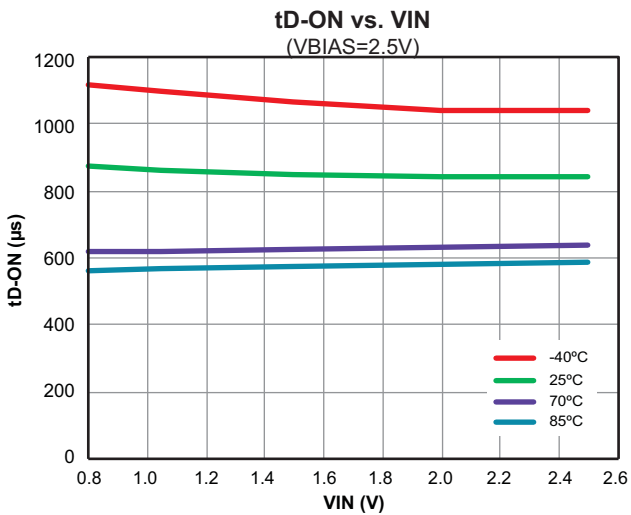
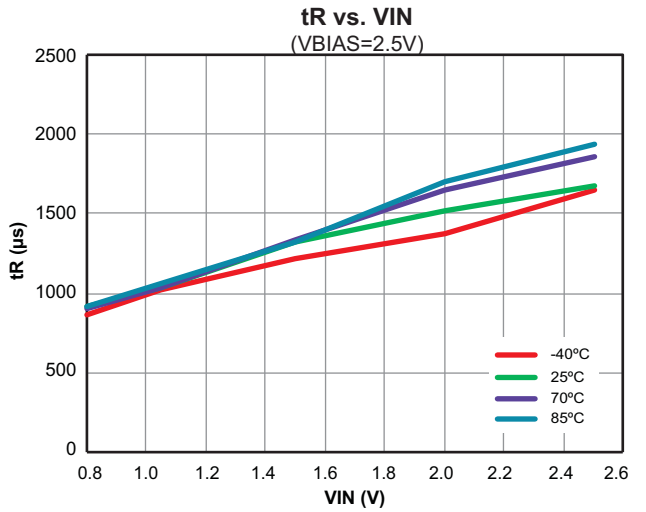
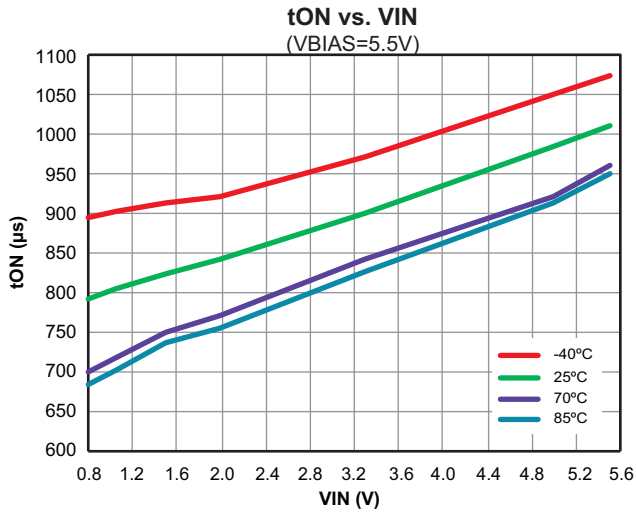
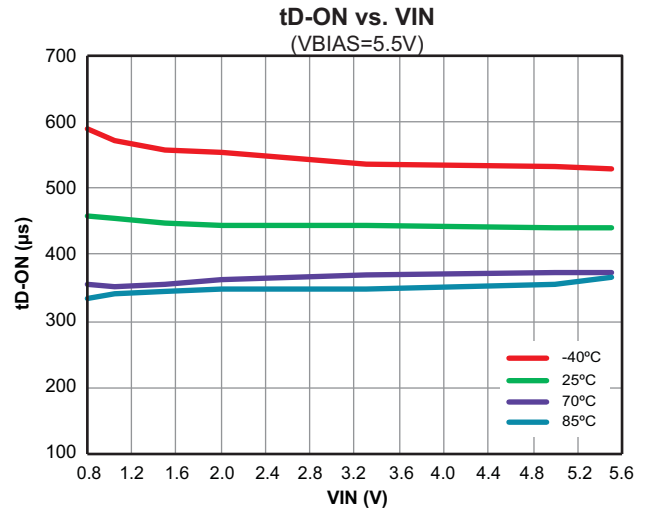
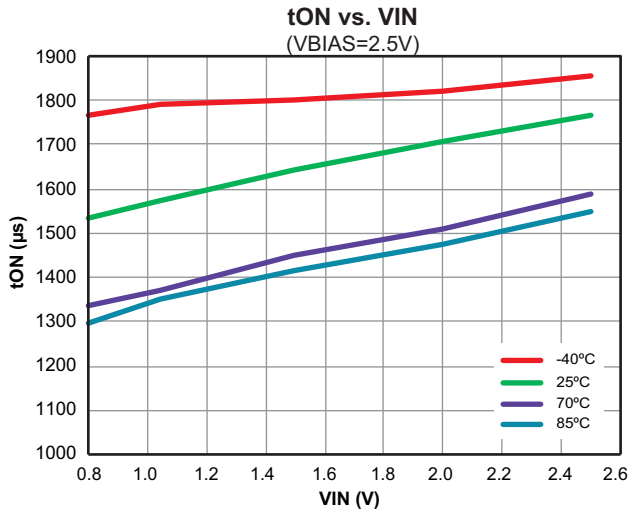
Test conditions:  $T_A = 25^\circ\text{C}$ ,  $C_{IN} = 1\mu\text{F}$ ,  $C_L = 0.1\mu\text{F}$  (unless otherwise specified).

Symbol	Parameter	Min.	Typ.	Max.	Units
<b>VIN = 1.05V, VBIAS = VON = 5V, RL = 10Ω</b>					
t <sub>ON</sub>	Turn-ON Time		800		μs
t <sub>D-ON</sub>	Turn-ON Delay time	350	500	650	
t <sub>R</sub>	Turn-ON Rise Time	350	500	650	
t <sub>OFF</sub>	Turn-OFF Time		2.8		
t <sub>F</sub>	Turn-OFF Fall Time		2.0		
<b>VIN = 1.5V, VBIAS = VON = 5V, RL = 10Ω</b>					
t <sub>ON</sub>	Turn-ON Time		830		μs
t <sub>D-ON</sub>	Turn-ON Delay time	336	480	624	
t <sub>R</sub>	Turn-ON Rise Time	420	600	780	
t <sub>OFF</sub>	Turn-OFF Time		2.5		
t <sub>F</sub>	Turn-OFF Fall Time		2.0		
<b>VIN = 1.05V, VBIAS = VON = 5V, IOU<sub>T</sub> = -6A</b>					
t <sub>ON</sub>	Turn-ON Time		1140		μs
t <sub>D-ON</sub>	Turn-ON Delay time		660		
t <sub>R</sub>	Turn-ON Rise Time		700		
t <sub>OFF</sub>	Turn-OFF Time		2.3		
t <sub>F</sub>	Turn-OFF Fall Time		0.5		
<b>VIN = 1.5V, VBIAS = VON = 5V, IOU<sub>T</sub> = -6A</b>					
t <sub>ON</sub>	Turn-ON Time		1120		μs
t <sub>D-ON</sub>	Turn-ON Delay time		630		
t <sub>R</sub>	Turn-ON Rise Time		770		
t <sub>OFF</sub>	Turn-OFF Time		2.0		
t <sub>F</sub>	Turn-OFF Fall Time		0.5		

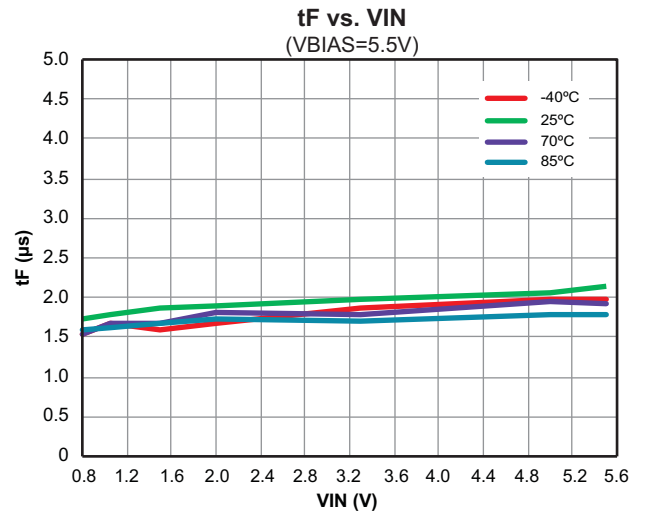
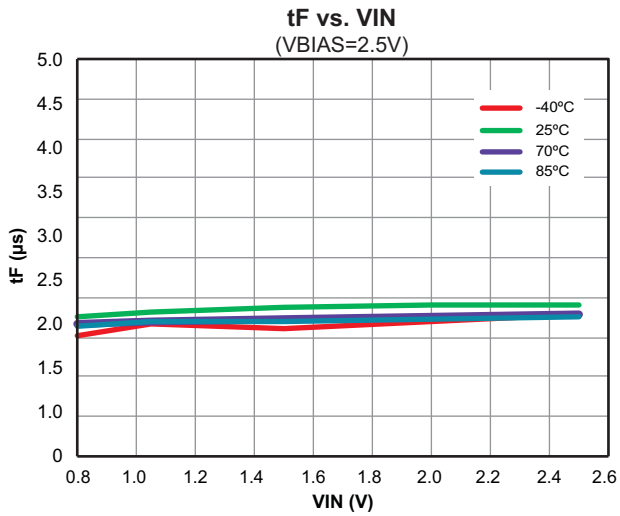
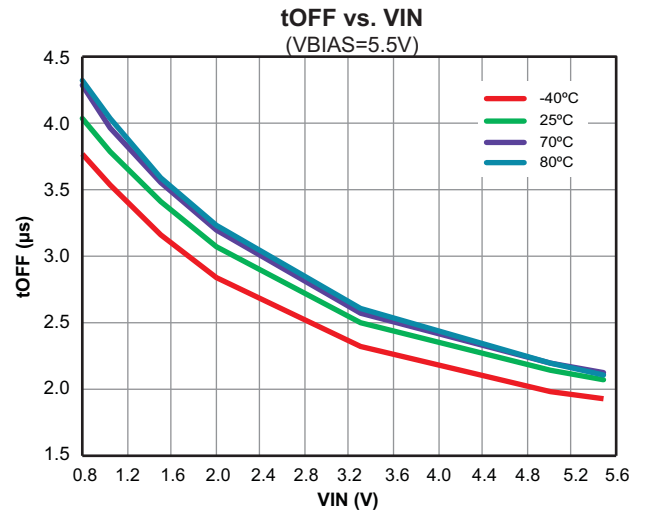
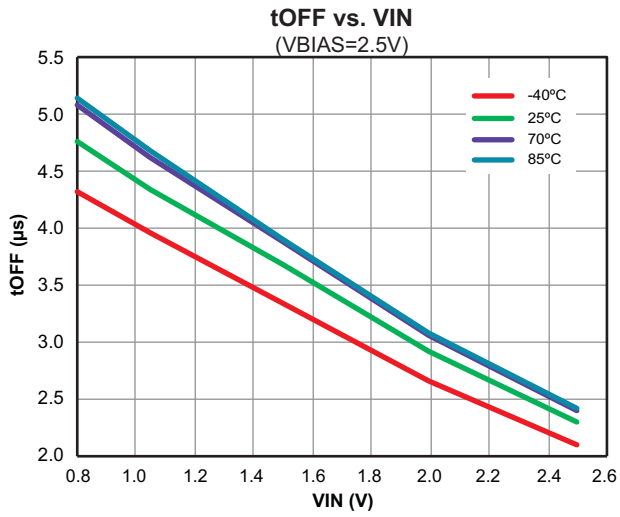
## Typical Characteristics



Typical Characteristics (Continued)

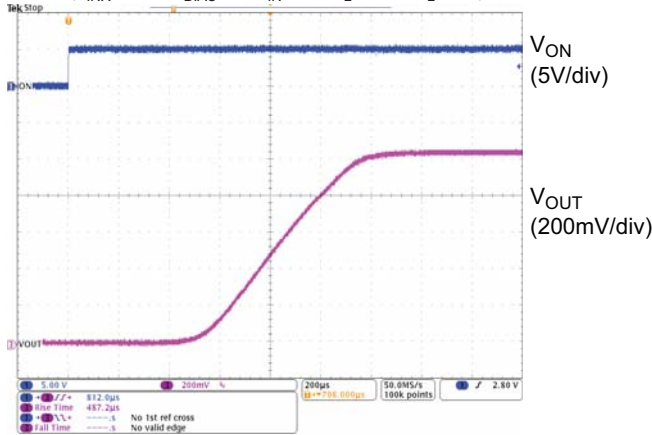


Typical Characteristics (Continued)

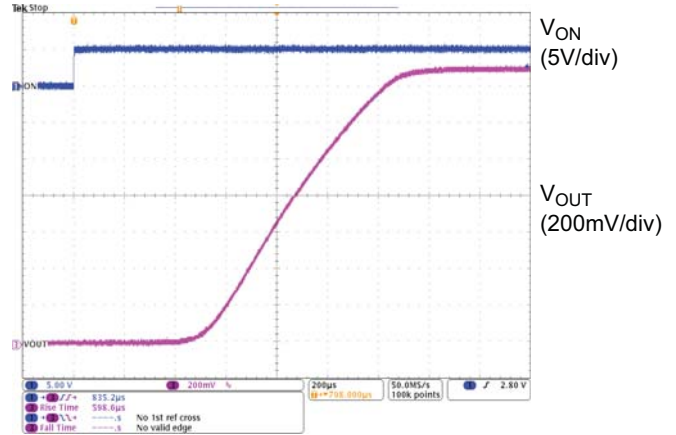


## Functional Characteristics

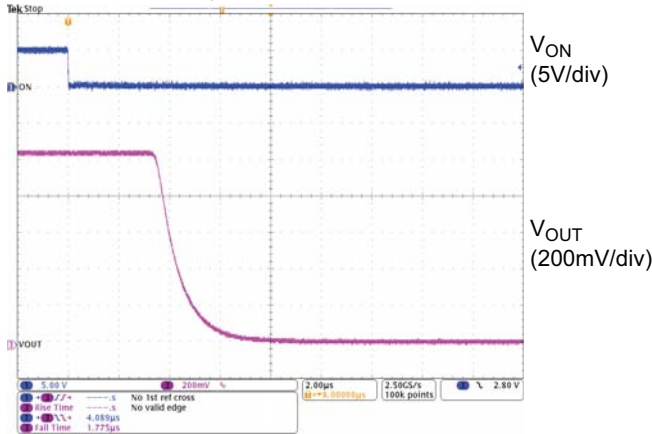
**Turn-ON & Turn-ON Rise Times**  
( $V_{INX}=1.05V$ ,  $V_{BIAS}=5V$ ,  $C_{IN}=1\mu F$ ,  $C_L=0.1\mu F$ ,  $R_L=10\Omega$ )



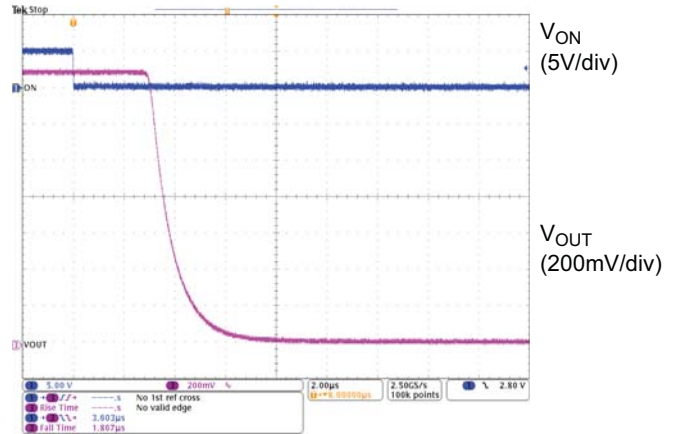
**Turn-ON & Turn-ON Rise Times**  
( $V_{INX}=1.5V$ ,  $V_{BIAS}=5V$ ,  $C_{IN}=1\mu F$ ,  $C_L=0.1\mu F$ ,  $R_L=10\Omega$ )



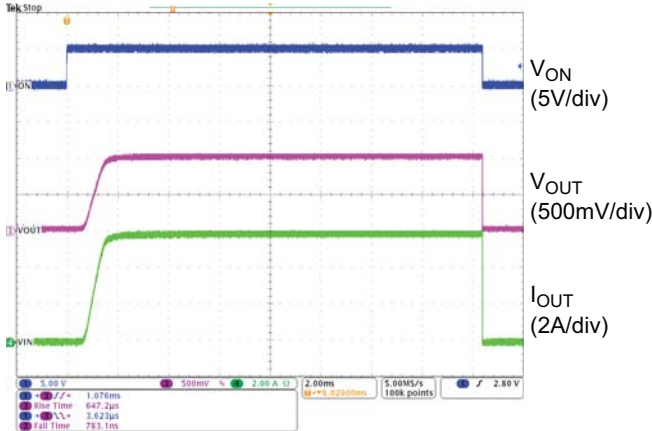
**Turn-OFF & Turn-OFF Fall Times**  
( $V_{INX}=1.05V$ ,  $V_{BIAS}=5V$ ,  $C_{IN}=1\mu F$ ,  $C_L=0.1\mu F$ ,  $R_L=10\Omega$ )



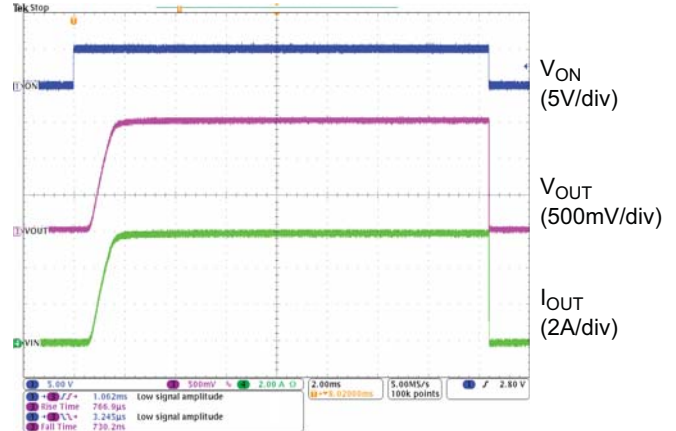
**Turn-OFF & Turn-OFF Fall Times**  
( $V_{INX}=1.5V$ ,  $V_{BIAS}=5V$ ,  $C_{IN}=1\mu F$ ,  $C_L=0.1\mu F$ ,  $R_L=10\Omega$ )



**Turn-ON & Turn-OFF at  $I_{OUT}=-6A$**   
( $V_{INX}=1.05V$ ,  $V_{BIAS}=5V$ ,  $C_{IN}=1\mu F$ ,  $C_L=0.1\mu F$ )



**Turn-ON & Turn-OFF at  $I_{OUT}=-6A$**   
( $V_{INX}=1.5V$ ,  $V_{BIAS}=5V$ ,  $C_{IN}=1\mu F$ ,  $C_L=0.1\mu F$ )





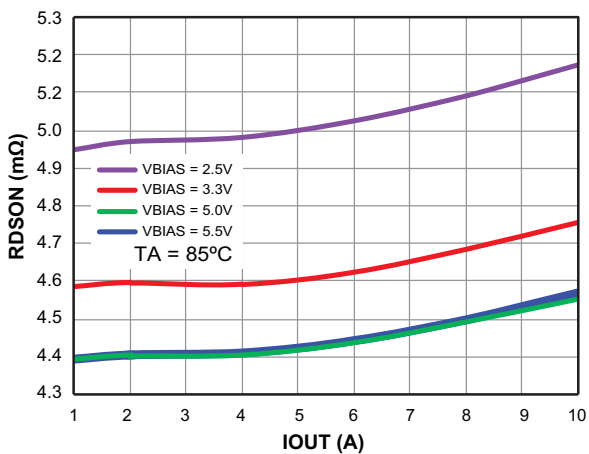
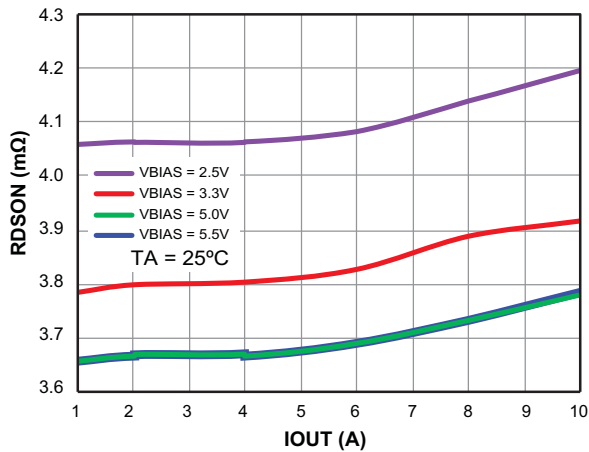
## Detailed Description

### ON/OFF Control

The AOZ1334DI-02 is enabled when the ON pin is on active high with 1.2V or above voltage. The device is disabled when the ON pin voltage is 0.5V or lower. The EN input is compatible with both TTL and CMOS logic.

### VBIAS Voltage Range

For optimal on-resistance of load switch, make sure the voltage is within 2.5V to 5.5V. On-resistance of load switch will be higher if the condition is not satisfied. Resistance curves of a typical sample device at  $V_{BIAS} = V_{IN}$  and at different output currents are shown as below.



## Applications Information

The basic AOZ1334DI-02 application circuit is shown in the first page. Component selection is explained below.

### Input Capacitor

A capacitor of 10μF or higher value is recommended to be placed close to the IN pins of AOZ1334DI-02. This capacitor can reduce the voltage drop caused by the in-rush current during the turn-on transient of the load switch. A higher value capacitor can be used to further reduce the voltage drop during high-current application.

### Output Capacitor

A capacitor of 10μF or higher value is recommended to be placed between the OUT pins and GND. The capacitance does not affect the turn-on slew rate. However, a larger capacitor makes the initial turn-on transient smoother.

### Thermal Considerations

To ensure proper operation, the maximum junction temperature of the AOZ1334DI-02 should not exceed 150°C. Several factors attribute to the junction temperature rise: load current, MOSFET on-resistance, junction-to-ambient thermal resistance, and ambient temperature. The maximum load current can be determined by:

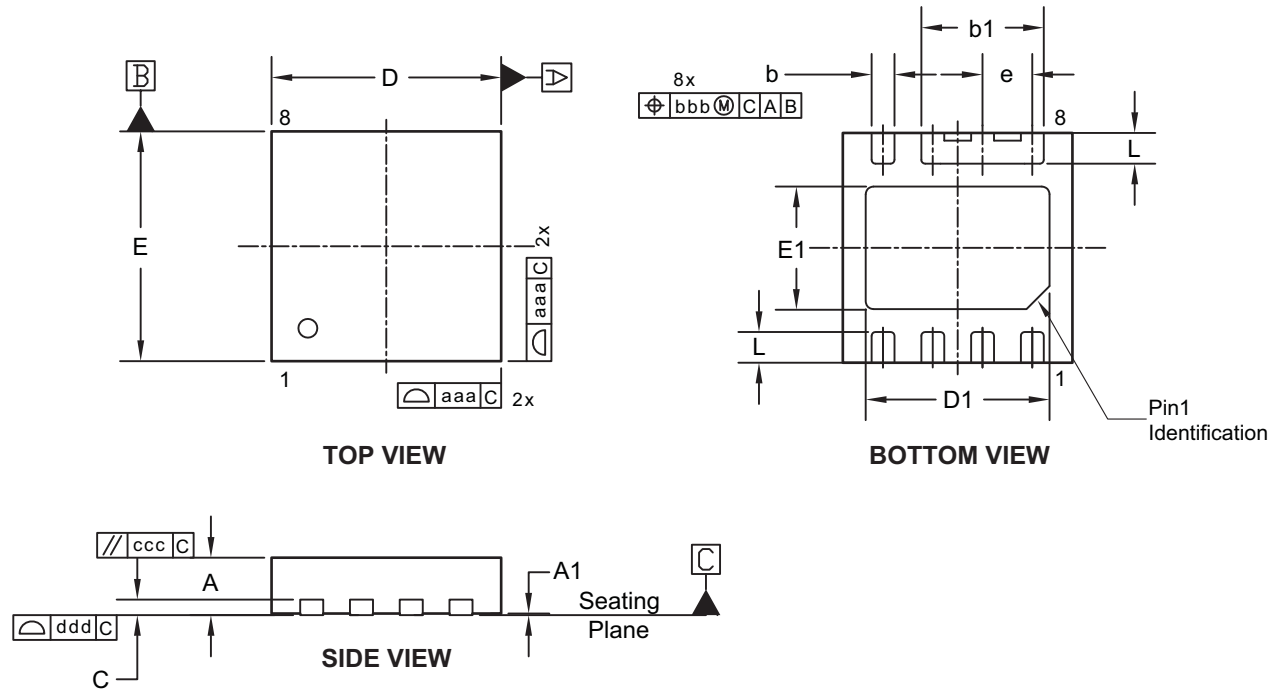
$$I_{LOAD(MAX)} = \sqrt{\frac{T_{J(MAX)} - T_C}{\Theta_{JC} \times R_{DS(ON)}}$$

It is noted that the maximum continuous load current is 10A. Exceeding the maximum continuous load current may cause permanent damage to the device.

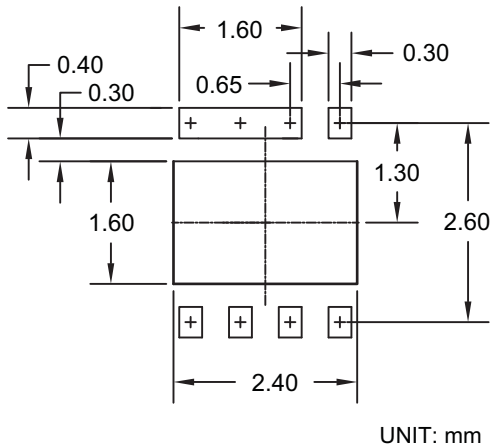
## Layout Guidelines

Good PCB is important for improving the thermal performance of AOZ1334DI-02. Place the input and output bypass capacitors close to the IN and OUT pins. The input and output PCB traces should be as wide as possible for the given PCB space. Use a ground plane to enhance the power dissipation capability of the device.

Package Dimensions, DFN3x3\_8L, EP1\_S



RECOMMENDED LAND PATTERN



Dimensions in millimeters

Symbols	Min.	Nom.	Max.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
b <sub>1</sub>	1.55	1.60	1.65
b	0.25	0.30	0.35
c	---	0.203	---
D	2.90	3.00	3.10
D <sub>1</sub>	2.35	2.40	2.45
E	2.90	3.00	3.10
E <sub>1</sub>	1.50	1.60	1.70
e	0.65 BSC		
L	0.35	0.40	0.45
R	0.20		
aaa	0.15		
bbb	0.10		
ccc	0.10		
ddd	0.08		

Dimensions in inches

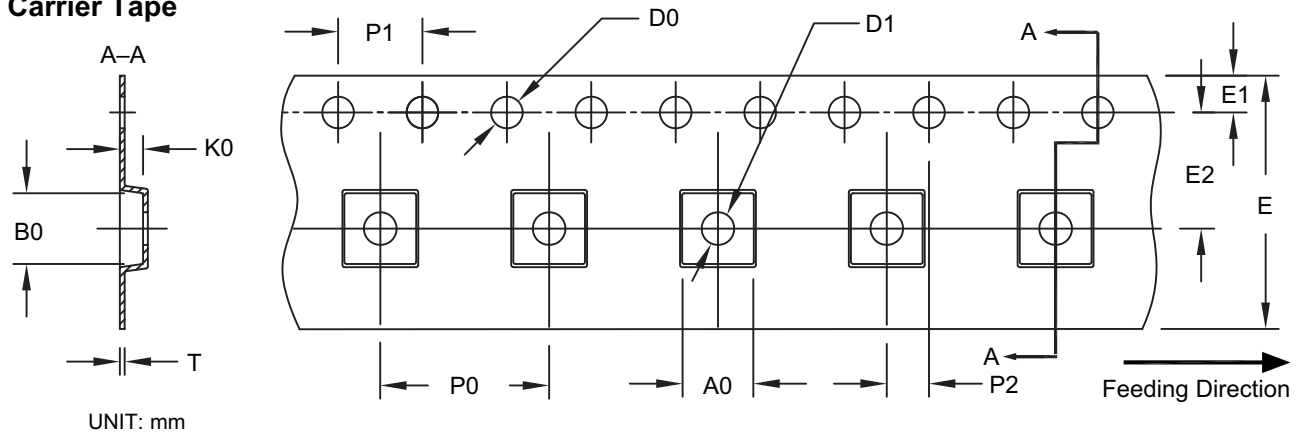
Symbols	Min.	Nom.	Max.
A	0.028	0.030	0.031
A1	0.000	0.001	0.002
b <sub>1</sub>	0.061	0.063	0.065
b	0.010	0.012	0.014
c	---	0.008	---
D	0.114	0.118	0.122
D <sub>1</sub>	0.093	0.094	0.096
E	0.114	0.118	0.122
E <sub>1</sub>	0.059	0.063	0.067
e	0.026 BSC		
L	0.014	0.016	0.018
R	0.008		
aaa	0.006		
bbb	0.004		
ccc	0.004		
ddd	0.003		

Notes:

1. Dimensions and tolerances conform to ASME Y14.5M-1994.
2. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.
3. Dimension  $b$  applies to metallized terminal and is measured between  $0.15$  mm and  $0.30$  mm from the terminal tip. If the terminal has the optional radius on the other end of the terminal, dimension  $b$  should not be measured in that radius area.
4. Coplanarity  $ddd$  applies to the terminals and all other bottom surface metallization.

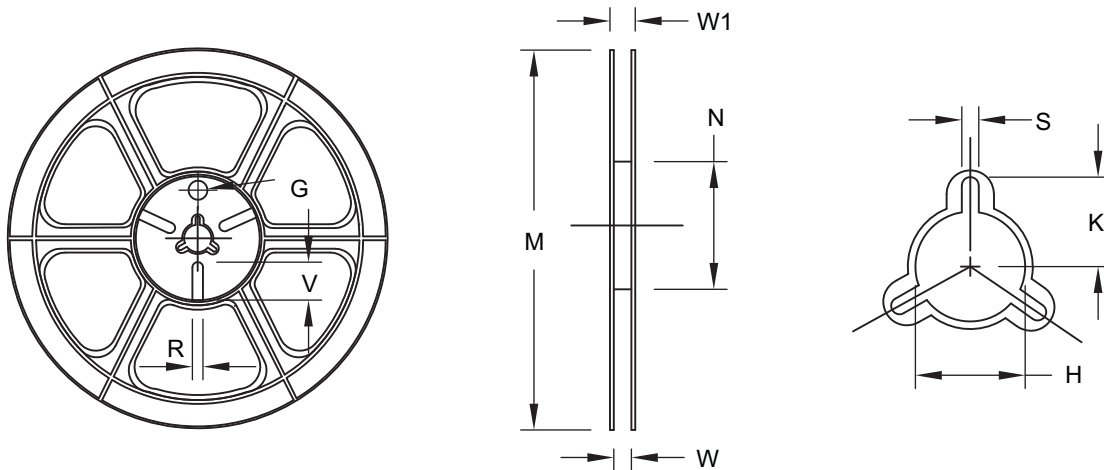
### Tape and Reel Dimensions, DFN3x3\_8L, EP1\_S

#### Carrier Tape



Package	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
DFN 3x3_EP	3.40 ±0.10	3.35 ±0.10	1.10 ±0.10	1.50 +0.10/-0.0	1.50 +0.10/-0.0	12.00 ±0.30	1.75 ±0.10	5.50 ±0.05	8.00 ±0.10	4.00 ±0.10	2.00 ±0.05	0.30 ±0.05

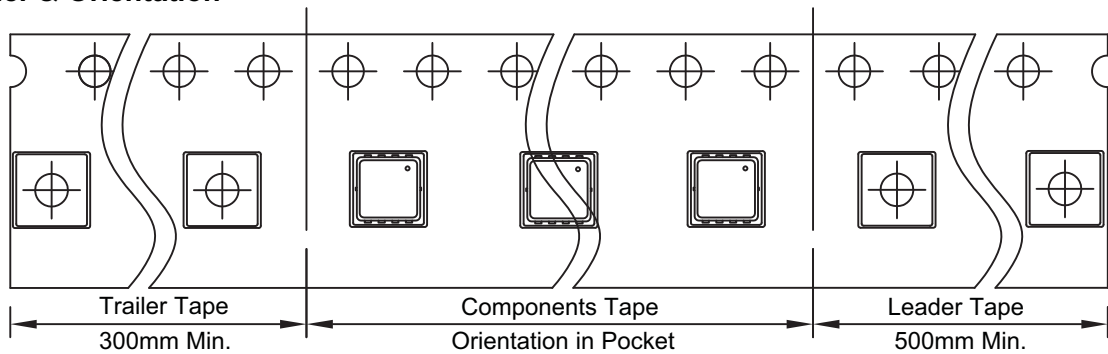
#### Reel



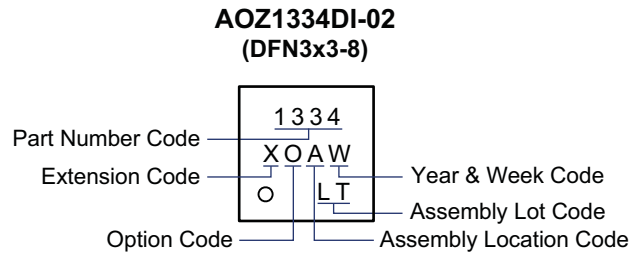
Tape Size	Reel Size	M	N	W	W1	H	K	S	G	R	V
12mm	ø330	ø330.00 ±0.50	ø97.00 ±0.10	13.00 ±0.30	17.40 ±1.00	ø13.00 +0.5/-0.2	10.60	2.00 ±0.50	N/A	N/A	N/A

#### Leader / Trailer & Orientation

Unit Per Reel:  
5000pcs



## Package Marking



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2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.